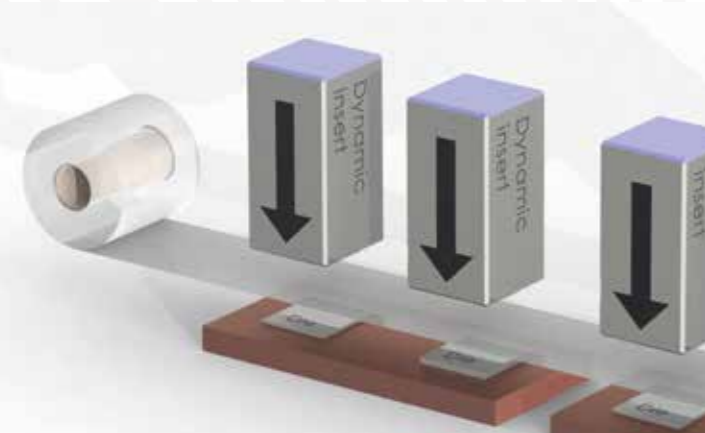
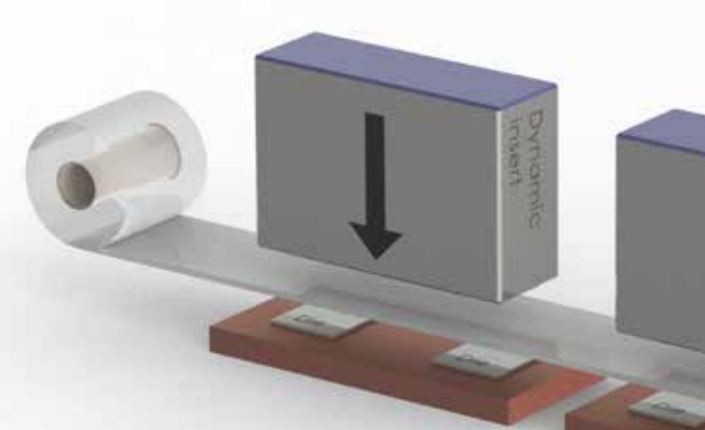


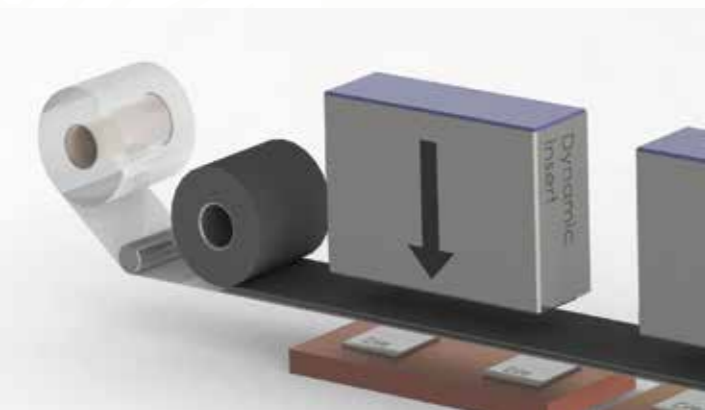
FILM HANDLING CONFIGURATIONS:



We use standard 50 um protection tapes between inserts and dies.



We can use up to 300 um protection tape which also serves to equalize pressure on dies which have a small die height difference.



Double film handling. A thick compensation layer can be handled in combination with a protective layer.

SINTERTOOL SOLUTIONS

The market for Ag sintering equipment and tools is characterized by many different designs and lay-outs, wide variety of products and die dimensions, process requirements due to use of different Ag- layer technologies and types (paste, film and other) and automation concepts. This requires different and tailor designed Ag-sinter tooling solutions. Boschman offers a wide range of Sinter tool solutions which fit

on all of our sintering systems. The core technology we use is dynamic insert technology (patented). The sintering pressure is precisely controlled and monitored during the complete sintering process. The sinter pressure is programmable via the MMI (man-machine-interface). The dynamic controlled inserts automatically compensate for die height differences, resulting in a controlled and predictable sinter force.



Contacts:

Europe

Boschman:
Marco Koelink
MarcoKoelink@Boschman.nl
Mobile +31646846563

USA

John Crane
jhrane@earthlink.net
Mobile : +6023631978

Asia-Pacific

Tng Thai Keng
tng.thai.keng@boschman.com.sg
Mobile: +6596714395
Johan Hamelink
JohanHamelink@boschman.nl
Mobile : +31651231091

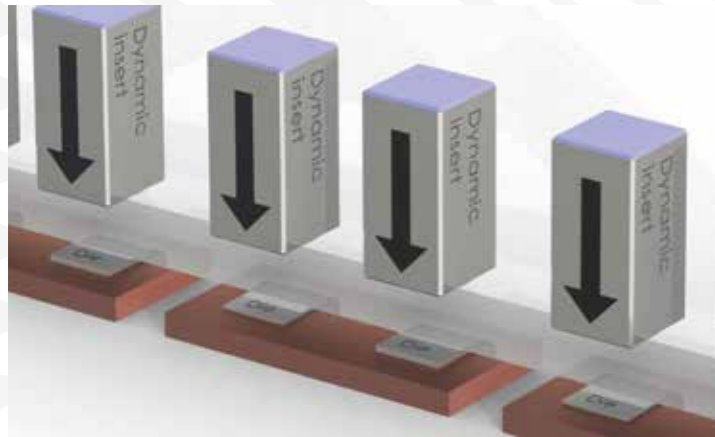
China

Han Lei
han.lei@boschman.com.sg
Mobile: +8618600581820

The Boschman dynamic insert technology provides:

Unique flexibility
Maximum control

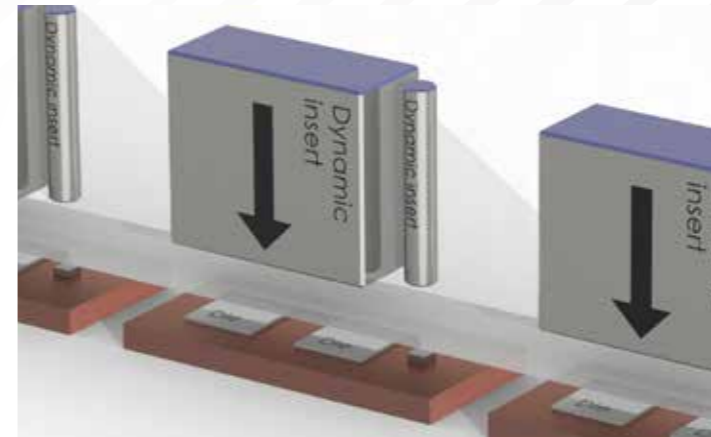
Individual dynamic insert technology:



Each insert presses on one individual die.

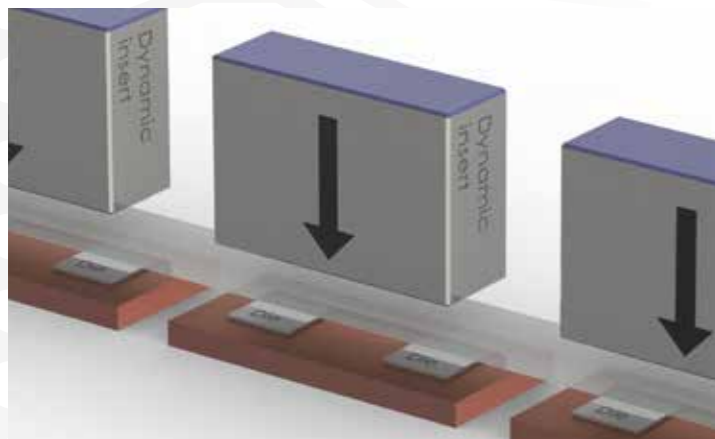
Ideal for modules which have different die heights.

Combination group and Individual dynamic insert technology:



I.e in case thermistors need to be sintered in one cycle together with IGBT/FRD dies a combination

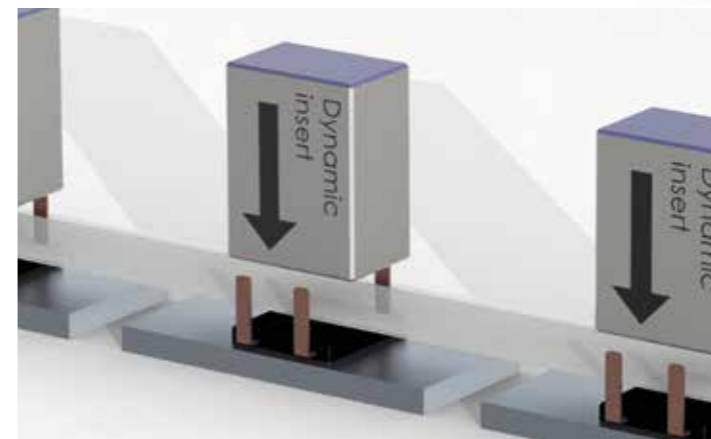
Group dynamic insert technology:



Each insert presses on more than one individual die.

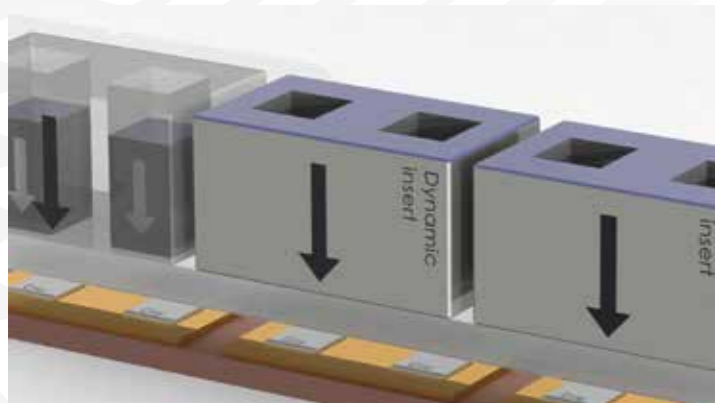
Ideal for modules which have multiple dies with same die height.

Package sintering to heatsink with individual dynamic insert technology:



Each insert presses on one individual package with exact pressure control.

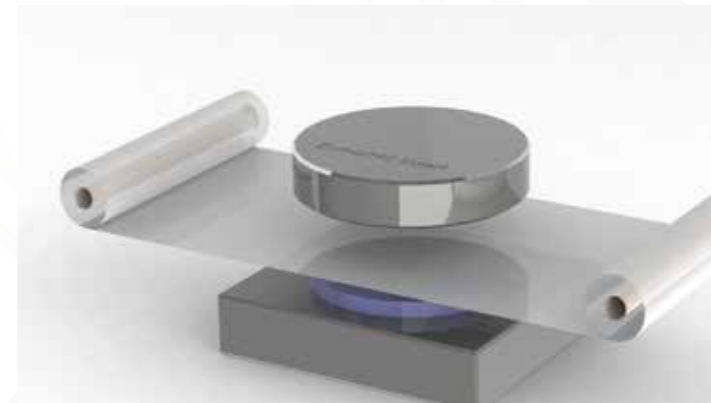
Insert in Insert dynamic insert technology:



In one sinter cycle we can sinter multiple areas and levels.

I.e. die to dbc and dbc to heatsink.

Flat tool with sintering:



For large area sintering without multiple different heights (e.g. wafers and thyristors)